

AMENDMENT TRANSMITTAL LETTER (Large Entity)  
 Applicant(s): Wei Pan, Yoshi Ono, David Russell Evans, and Sheng  
 Teng Hsu

Docket No.  
 SLA0515

Serial No 09/819,296	Filing Date March 27, 2001	Examiner Huling K. Vu	Group Art Unit 2811
-------------------------	-------------------------------	--------------------------	------------------------

Invention: Multi-Layered Barrier Metal Thin Films for Cu Interconnect by ALCVD

APR 4 2005

TO THE COMMISSIONER FOR PATENTS:

Transmitted herewith is an amendment in the above identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER OF EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	17 -	20 =	0	x \$50.00	\$0.00
INDEP. CLAIMS	3 -	3 =	0	x \$200.00	\$0.00
Multiple Dependent Claims (check if applicable)					\$0.00
		TOTAL ADDITIONAL FEE FOR THIS AMENDMENT			\$0.00

No additional fee is required for amendment.

Please charge Deposit Account No. 19-1457 in the amount of \$0.00.

A duplicate copy of this sheet is enclosed.

A check in the amount of \_\_\_\_\_ to cover the filing fee is enclosed.

The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 19-1457.

A duplicate copy of this sheet is enclosed.

Any additional fees required under 37 C.F.R. 1.16.

Any patent application processing fees under 37 C.F.R. 1.17.

Dated: April 4, 2005

David C. Ripma, Reg. No. 27,672

I hereby certify that this correspondence is being facsimile transmitted to the United States Patent and Trademark Office under 37 C.F.R. §1.8 at Fax No. (703) 872-9306 on April 4, 2005.

David C. Ripma, Reg. No. 27,672

Note: Each paper must have its own certificate of transmission, or this certificate must identify each submitted paper. The papers submitted include:

- This Amendment Transmittal Letter (Include Duplicate)
- Response under 37 CFR § 1.111
- Attachments
- 

2 page(s)  
 14 page(s)  
 0 page(s)  
 pages

Total pages, including this Transmittal: 16

AMENDMENT TRANSMITTAL LETTER (Large Entity)  
 Applicant(s): Wei Pan, Yoshi Ono, David Russell Evans, and Sheng  
 Teng Hsu

Docket No.  
 SLA0515

Serial No	Filing Date	Examiner	Group Art Unit
09/819,296	March 27, 2001	Huling K. Vu	2811

Invention: Multi-Layered Barrier Metal Thin Films for Cu Interconnect by ALCVD

RECEIVED - U.S. PATENT AND TRADEMARK OFFICE

**TO THE COMMISSIONER FOR PATENTS:**

APR 04 2005

Transmitted herewith is an amendment in the above identified application.

The fee has been calculated and is transmitted as shown below.

**CLAIMS AS AMENDED**

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER OF EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	17 -	20 =	0	x \$50.00	\$0.00
INDEP. CLAIMS	3 -	3 =	0	x \$200.00	\$0.00
Multiple Dependent Claims (check if applicable)					\$0.00
				TOTAL ADDITIONAL FEE FOR THIS AMENDMENT	\$0.00

No additional fee is required for amendment.

Please charge Deposit Account No. 19-1457 in the amount of \$0.00.

A duplicate copy of this sheet is enclosed.

A check in the amount of \_\_\_\_\_ to cover the filing fee is enclosed.

The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 19-1457.

A duplicate copy of this sheet is enclosed.

Any additional fees required under 37 C.F.R. 1.16.

Any patent application processing fees under 37 C.F.R. 1.17.

Dated: April 4, 2005

David C. Ripma, Reg. No. 27,672

I hereby certify that this correspondence is being facsimile transmitted to the United States Patent and Trademark Office under 37 C.F.R. §1.8 at Fax No. (703) 872-9306 on April 4, 2005.

David C. Ripma, Reg. No. 27,672

Note: Each paper must have its own certificate of transmission, or this certificate must identify each submitted paper. The papers submitted include:

This Amendment Transmittal Letter (Include Duplicate)

2 page(s)

Response under 37 CFR § 1.111

14 page(s)

Attachments

0 page(s)

pages

Total pages, including this Transmittal: 16

APR 04 2005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:	)	PATENT APPLICATION
	)	
Inventors: Wei Pan,	)	
Yoshi Ono,	)	Attorney Docket No.
David Russell Evans,	)	SLA0515
and Sheng Teng Hsu	)	
	)	
Serial No.: 09/819,296	)	
	)	
Filed: March 27, 2001	)	Group Art Unit 2811
	)	
Title: MULTI-LAYERED	)	
BARRIER METAL	)	Examiner: Vu, Hung K.
THIN FILMS FOR Cu	)	
INTERCONNECT	)	Confirmation No.: 4061
BY ALCVD	)	
	)	
	)	

## RESPONSE UNDER 37 C.F.R. § 1.111

Mail Stop Amendments  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to an Office Action dated January 25, 2005, please amend and reconsider the above-identified application as follows.

Amendments to the claims begin on page 2 of this paper.

Remarks begin on page 8 of this paper.